**Next Wave Engineering Simulation**

**Engineering Simulation Solutions to Optimize Products and Metal Forming Processes**

Half-day seminars:
- **Wednesday, August 28, 2002, Detroit**
- **Thursday, August 29, 2002, Chicago**

This is a great opportunity to hear about our vision, technologies and products. Learn how customers use our solutions to increase quality and streamline design cycles. It’s the Next Wave of Engineering Simulation!

**Engineering Simulation:**
Optimizing Product Designs & Processes

**Sheet metal forming simulation processes**

**Die Face Engineering with DYNAFORM:**
From part design to tooling design

**Bridging sheet metal forming and structural integrity simulations**

**Sun HPC Technology:**
Grid computing, Technical Computing Portals, and high-end visualization

**ANSYS in the Race Car Industry:**
David Finch, President, RAETECH (Detroit session)

**Register Today at this URL:**

http://www.sun.com/us-signup

Login: technical
Password: computing

**Space is Limited!**
Register early

**AGENDA:**

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<tr>
<td>Registration &amp; Continental Breakfast</td>
<td>9:00 a.m.</td>
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<td>Sessions:</td>
<td>9:30 - 12:40</td>
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<td>Lunch</td>
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**NEW PRODUCT SHOWCASE**

- **Sun™ V880 and Sun Blade™ 2000 Scalable MCAE Solutions**
- **The ultimate, up-front simulation tool from ANSYS Inc.**
- **The new Die Face Engineering module for eta/DYNAFORM**
Sponsor Info:

Sun Microsystems, Inc.
Sun Microsystems is the revenue leader in Technical Computing, for workstations and servers (all operating systems - IDC 2001). Sun recently introduced several innovative software solutions for technical users, including: Sun™ Grid Engine for resource management; the Sun Technical Computing Portal to facilitate access and collaboration; high-end workstation- and server-based graphics/visualization products; storage products; and cluster solutions — including a newly announced Sun Cobalt Linux offering.
- We Make the Net Work.

ANSYS Inc.
DesignSpace is the ultimate, up-front CAE simulation tool that allows designers to perform engineering simulations early in the design process. Compatible with various 3-D CAD systems and designed with a highly intuitive GUI, DesignSpace can simulate/optimize design performance for stress, fatigue, temperature and vibrations. Designers may use this tool to virtually test their parts and assemblies under likely loads and environments. DesignSpace also offers an Internet-ready, engineering reporting capability to facilitate collaboration with customers, colleagues, suppliers and partners.

ETA, Inc.
DYNAFORM’s new DFE (Die Face Engineering) module is a complete die face engineering process used to create the tooling design, including binder and addendum, from the part geometry within the DYNAFORM interface. The DFE module contains a set of automated tools such as reverse trimming functions, part-tipping, and binder and addendum generators to guide the designer.

Detroit Seminar (8/28)
The Westin-Southfield
(M10 Highway at Evergreen-10 Mile Road exit)
1500 Town Center
Southfield, MI 48075
tel: 248-827-4000

Detroit Contact:
John Sears
e-mail: john.sears@sun.com
phone: 248-359-2826

Chicago Seminar (8/29)
The Hyatt-Schaumburg
1800 E. Golf Road
Schaumburg, IL 60173
tel: 847-605-1234

Chicago Contact:
Jarrod Krug
e-mail: jarrod.krug@sun.com
phone: 312-214-6283